

ABSTRACT

A system may include an integrated circuit die, an integrated circuit package coupled to the integrated circuit die, mold compound in contact with the integrated circuit die and the integrated circuit package, and an interconnect coupled to the integrated circuit package. A
5 first portion of the interconnect may be in contact with the mold compound, a second portion of the interconnect might not contact the mold compound, and a third portion of the interconnect may be in contact with the integrated circuit package.